

ABSTRACT

An electrically conductive paste used for forming wiring conductors, such as via holes (15) disposed on a multilayer ceramic substrate (11), is provided, wherein the temperature range, in which sintering is effected in a firing step, can be controlled relatively optimally. The electrically conductive paste contains a metal powder, a glass frit, and an organic vehicle. An inorganic component, which is not sintered at a sintering temperature capable of sintering the ceramic layers (12) included in the multilayer ceramic substrate (11) in the firing step, is disposed on particle surfaces of the metal powder. The glass frit has a softening point 150°C to 300°C lower than the above-described sintering temperature.